The Vision The Cell Architecture Summary & Conclusion

The Cell Processor Computing of tomorrow or yesterday?

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Torsten Höfler Department of Computer Science TU Chemnitz The Cell Processor

Outline



- The Cell Architecture
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 - The Synergistic Processing Element (SPE)
 - The Element Interconnect Bus (EIB)
 - The I/O Interconnect FlexIO
 - The Memory Interface Controller (MIC)
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The Researchers

- started in mid 2000 by Sony Toshiba and IBM
- Sony has PS2 arch needs chip for PS3
- Toshiba has memory experience needs Chips for HDTV
- IBM has technical knowledge in processor manufacturing
- billions of dollars have been invested
- $\bullet \ \Rightarrow \text{high throughput multi purpose processor}$

Known Problems to Overcome

- memory latency gap
- instruction latency gap (control logic)
- old fashioned x86 arch
- hardware architecture other than ISA
- implicit mem hierarchy (caching)

Main Changes compared to x86

- RISC design
- in order CPU (no OOO)
- SoC design (different cores)
- heterogeneous Multiprocessing



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1st Patent - Ken Kutaragi (Sony,1999)

- cell = software or hardware cell
- software cell = program + data
- hardware cell = execution logic + local memory
- hardware cells process software cells
- no fixed architecture (network distribution)
- cell computer is created ad-hoc (multiple devices)



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- Heterogeneous Multiprocessing 9 Core Processor
- SPU Synergistic Processing Unit
- MFC Memory Flow Controller
- SPE Synergistic Processing Element (=SPU+MFC)
- PPE PowerPC Processing Element
- 1PPE + 8 SPEs = Cell Processor
- 9 full blown CPUs







- connected via EIB Element Interconnection Bus
- FlexIO IO/Processor Interconnect (BIC)
- MIC dual port XDR Memory Interface
- hardware DRM :-(
- interrupts controller routes only to PPE
- effective NoC (Network on Chip)
- $\bullet \ \Rightarrow \text{single precision 256 GFlops peak}$







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Cell Chip Block Diagram





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First Prototype

- 90nm SOI, 8 copper layers
- 234 Mill. Transistors
- 60-80 W (prototype)
- only 6-7 SPEs enabled (manufacturing errors)
- IBMs virtualization technology
- 1.1V, 4GHz





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- dual-threaded (SMT) 64 bit Power Architecture
- includes VMX (aka Altivec) ISA
- simple architecture, only in-order execution
- super-scalar with deep 2-way pipeline (>20)
- 2 instructions issued per cycle
- 32kB+32kB L1, 512 kB L2 Cache
- supports virtualization \rightarrow logical partitioning (memory, I/O, time)
- simplified Power Architecture

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- fully blown vector CPUs with own RAM
- ISA: not VMX compatible!
- ISA: 32 bit fixed length
- 21 Mill transistors (14 Mill SRAM, 7 Mill logic)



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- no branch prediction or scheduling logic (software)
- two independent short and simple pipes
- can issue two instructions in parallel
- one memory and one SIMD computation
- strictly in order
- instructions work with 128 bit combound data
- 4 SP FP units (not fully IEEE754 compliant 32GFlops)
- slow DP arithmetic (fully IEEE754 3-4GFlops)
- 4 INT units (32 GFlops)

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Image: A matrix

- 256kB local storage (LS) memory
- accessable in 128bit lines
- 128 128bit registers (2 cycles latency)
- registers are layered (hold all data types)
- no virtual memory, no coherency
- no processing in main memory
- DMA to move data between LS and main memory
- MFC connects to EIB, acts like MMU + synch



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Opteron: 3GHz, 3 FP units - SPE: 4GHz, 4 SP FP units





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- four 128 bit wide concentric rings
- optimized for 1024 bit blocks
- 96 byte/cycle
- buffered point-to-point ring (cmp. SCI)
- SPE buffers and routes
- scalable (more SPEs increase latency)
- guaranteed bandwidth of 1/# devices
 → Real Time capable



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- 12 unidirectional byte-wide lanes
- 96 pairs in the whole
- 6.4 Gb/s per lane (76.8 Gb/s in the whole)
- 7 lanes (44.8 GB/s) out, 5 lanes (32 GB/s) in
- coherent (cc-NUMA) and non coherent links
- also used as processor interconnect (cmp. HT)
- connect two processors glueless
- needs switch for more

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- two channel Rambus XDR Memory 25.2 GB/s
- ECC protected (why?)
- PPE/SPE have conventional protection system to access main memory (cmp. MMU)
- PPE/SPE use virtual addresses
- $\bullet \$ no cache \rightarrow moved to software

- no abstraction layer like x86
- difficult programming and optimization
- same problems as for Multi-Core or SMPs
- direct programming of SPEs, 256kb storage + 128 Regs
- no need for assembly but it is available :)
- programmable in C/C++
- SPEs are allocated in software
- SPE virtualization by OS? (more SPE tasks as SPEs)
- PPE code must only be PPC970
 - \rightarrow Linux already running
- SPE code must be self-contained
- autoparallelizing compiler from IBM: Octopile



Programming Models:

- job queue
- self multitasking SPE
- Stream Processing
- Software Managed Cache
- MPI?



Let the Cells glow!



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The Cell Processor

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- general purpose Power CPU with 8 vector processors (SPEs)
- RISC approach moving functionality to software
 → more complicated compiler (cmp. VLIW)
- very fast I/O System coupled with task distribution
- 560 Cells to get to the top of the top500 (theoretically)
- Realtime capabilities because of independent SPE
- intended to be the standard of tomorrow
- (hopefully) integrated in PS3 and Toshiba TVs (hdtv) in 2006



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Resources / Additional Information:

- http://www.research.scea.com/research/html/CellGDC05/
- http://www.blachford.info/computer/Cells/Cell0.html
- http://www.research.ibm.com/cell/
- http://www.cell-industries.com/
- http://www-306.ibm.com/chips/techlib/techlib.nsf/products/Cell
- http://www-128.ibm.com/developerworks/power/cell/

